

ABSTRACT OF THE DISCLOSURE

A method for manufacturing a plurality of metal core substrates for a surface-mounted light emitting diode includes steps of adhering a pair of metal base plates and a plurality of insulation layers, adhering a pair of metal base plates interposing one of the insulation layers as a first insulation layer to form a set plate, stacking a plurality of set plates between a pair of guide plates, interposing a separation gap between adjacent set plates to form a set plate block, cutting the set plate block in a stacking direction to form a set plate aggregation, securing a second insulation layer to a cut surface of the set plate aggregation, securing a circuit pattern aggregation layer to the second insulation layer to form a metal core substrate aggregation, forming a separation groove on the circuit pattern aggregation layer between adjacent set plates, corresponding to the separation gap, forming a groove along a center line of the set plate to separate the set plate into first and second circuit pattern aggregations, forming electrodes on both sides of the substrate aggregation, separating the guide plates, and cutting off the substrate aggregation into independent substrates.